

10/16/01
JC682 U.S. PTO

10-18-01

Atty. Docket No. AMAT/6072/CALB/ECD/PJS

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JC971 U.S. PTO
09/981505
10/16/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
Assistant Commissioner of Patents and Trademarks
Washington, D.C. 20231

Re: Inventor(s): DONALD J. K. OLGADO; JOSEPH J. STEVENS and ALEXANDER LERNER
Title: PLANARIZATION OF METAL LAYERS ON A SEMICONDUCTOR WAFER
THROUGH NON-CONTACT DE-PLATING AND CONTROL WITH ENDPOINT DETECTION

Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 31 pages.
- ☒ Drawings totaling 7 pages, ☒ Formal Informal.
- ☒ Executed Declaration and Power of Attorney.
- ☐ Information Disclosure Statement w/ Form 1449 and References.
- ☒ Assignment of the invention to **Applied Materials, Inc.**
- ☒ Assignment Recordation Cover Sheet

FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	54	-20=	34	x \$18.00	--\$612.00
Independent Claims	4	-3=	1	x \$84.00	--\$ 84.00
Basic Filing Fee				\$740.00	\$740.00
TOTAL FEES					\$1,436.00

- ☒ The Commissioner is hereby authorized to charge **\$1,436.00** to Deposit Account No. **50-1074/6072/CALB/ECD/PJS**.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. **50-1074/6072/CALB/ECD/PJS**. A duplicate copy of this transmittal is enclosed.
- ☒ Please address all future correspondence to:

**PATENT COUNSEL
APPLIED MATERIALS, INC.,
Legal Affairs Department
P.O.BOX 450A
Santa Clara, CA. 95052**

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231.
Express Mail Receipt No. EV041915462US

Date of Deposit 10-16-01

Signature Robert W. Mulcahy

Respectfully submitted,

Robert W. Mulcahy
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